

Low Melting Point Thermal Interface Materials TIC™ 800G Series



TIC™800G Series is low melting point phase change thermal interface material.

At 50°C, TIC™800G Series begins to soften and flow, filling the microscopic irregularities of both the thermal solution and the integrated circuit package surface, thereby reducing thermal resistance.

TIC™800G Series is a flexible solid at room temperature and freestanding without reinforcing components that reduce thermal performance.







For Lowest Thermal Resistance

- 0.014℃-in²/W thermal resistance
- » Naturally tacky at room temperature, no adhesive required
- Flows but doesn't run like grease

Application

- Notebook and Desktop PCs
- Set Top Box
- Memory modules
- » Micro heat pipe thermal solutions

| Typical Properties of TIC800G Series | | | | | |
|---------------------------------------|--------------------------------|---------------------|---------------------|-------------------|--------------------------|
| Product Name | TIC805G | TIC808G | TIC810G | TIC816G | Test Method |
| Color | Gray | | | | Visual |
| Thickness | 0.005" (0.127mm) | 0.008" (0.203mm) | 0.010" (0.254mm) | 0.016" (0.4mm) | ASTM D374 |
| Density | 2.5g/cc | | | | Helium Pycnometer |
| Temperature Range | – 25 °C ~ 125 °C | | | | ****** |
| Phase Change Softening Temperature | 50 ℃ ~ 60 ℃ | | | | ****** |
| Thermal Conductivity | 5.0W/mk | | | | ASTM D5470 (modified) |
| Thermal Impedance@50psi | 0.014°C-in²/W | 0.020°C-in²/W | 0.038°C-in²/W | 0.045°C-in²/W | ASTM D5470 (modified) |

Standard Thicknesses:

0.005"(0.127mm) 0.008"(0.203mm) 0.010"(0.254mm) 0.016"(0.4mm)

Consult the factory alternate thickness.

Standard Sizes:

10" x 16"(254mm x 406mm) 16" X 400' (406mm X 121.92M)

TIC™800G Series are supplied with a white release paper and a bottom liner.

TIC™ 800G Series is available in kiss cut an extended pull tab liner or individual die cut .shapes

Peressure Sensitive Adhesive:

Peressure Sensitive Adhesive is not applicable for TIC™800G Series products.

If you want to know our thermal Products, you can visit our website . http://www.ziitek.com



Gap Fillers | Pouring sealant | Silicon tape | Thermally Conductive paste | Flake graphite | Thermally Conductive Insulators | Ceramic heat sinks |
| Thermally Conductive plastic | Thermally Conductive Adhesive Tapes
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